

L Number	Hits	Search Text	DB	Time stamp
21	35	"257698"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:24
22	1784	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:25
23	2462	257/774	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:25
24	2274	438/637	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:26
25	314	438/667	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:26
26	300	438/668	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:28
27	6240	257/698 257/774 438/637 438/667 438/668	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:28
28	995	(257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:43
29	955	((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:29
30	656	((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:44
31	189	((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:32
32	18	((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:39
33	8	5767580.URPN.	USPAT	2002/12/27 14:35
34	24	("3339274" "3461357" "3811186" "4151543" "4545610" "4664309" "4700276" "4717066" "4801992" "4825284" "4857482" "4912545" "4926241" "5006673" "5014111" "5077633" "5108950" "5111279" "5196726" "5311402" "5404047" "5468999" "5477086" "5525838").PN.	USPAT	2002/12/27 14:36
35	21	5477086.URPN.	USPAT	2002/12/27 14:36
36	7	("3339274" "3461357" "4151543" "4857482" "5014111" "5196726" "5311402").PN.	USPAT	2002/12/27 14:38

41	171	(((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
42	2	6187652.URPN.	USPAT	2002/12/27 14:46
43	0	6486409.URPN.	USPAT	2002/12/27 14:47
44	6	("5210940" "6013876" "6080936" "6187652" "6198634" "6252176").PN.	USPAT	2002/12/27 14:47
45	1	6198634.URPN.	USPAT	2002/12/27 14:48
46	23	("4814855" "5121299" "5191174" "5239448" "5306546" "5316788" "5373627" "5468681" "5477082" "5479703" "5504035" "5583321" "5591941" "5633533" "5637832" "5675889" "5715144" "5764485" "5773884" "5784262" "5796589" "5812378" "5999415").PN.	USPAT	2002/12/27 14:48
47	2	6013876.URPN.	USPAT	2002/12/27 14:57
48	9	5210940.URPN.	USPAT	2002/12/27 15:00
49	9	("3742597" "4487659" "4512829" "4528259" "4529477" "4720324" "4861640" "4996391" "5129142").PN.	USPAT	2002/12/27 15:02
50	11	5900674.URPN.	USPAT	2002/12/27 15:14
51	7	("4641222" "4835704" "4894115" "5161093" "5449427" "5454904" "5527741").PN.	USPAT	2002/12/27 15:15
52	4	5783866.URPN.	USPAT	2002/12/27 15:16
53	3	("4082394" "4322778" "5569960").PN.	USPAT	2002/12/27 15:17
54	2	"5962922"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
55	4	"5923535"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
56	24	"5097318"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
57	31	"5404044"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
58	9	"5796163"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
59	5	"6187652"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:21
60	4	"6114769"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:21

62	76	("5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769") not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:22
63	22	("5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769") not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap)))) not "5097318" not "5404044"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:22
64	2	6114769.URPN.	USPAT	2002/12/27 15:23
65	13	("5468999" "5551627" "5691041" "5796590" "5838069" "5844316" "5859474" "5861678" "5869904" "5883438" "5892288" "5921462" "5930889").PN.	USPAT	2002/12/27 15:24
66	8	5936848.URPN.	USPAT	2002/12/27 15:25
67	5	("5241133" "5450290" "5512786" "5640047" "5689091").PN.	USPAT	2002/12/27 15:27
61	78	"5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:29
68	7	("4664962" "5315072" "5404044" "5406034" "5541368" "5689091" "5783865").PN.	USPAT	2002/12/27 15:30
69	8	4664962.URPN.	USPAT	2002/12/27 15:31
70	5	("3384957" "4045863" "4366229" "4436583" "4512829").PN.	USPAT	2002/12/27 15:31
72	2747	257/773	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:42
73	4597	257/774 257/773	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:43
74	722	(257/774 257/773) and (solder adj (ball bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:43
75	709	((257/774 257/773) and (solder adj (ball bump))) and (substrate carrier ((circuit wiring) adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:46
76	336	((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:47
77	325	((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))) and (chip die ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:48

78	246	((((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))) and (chip die ic)) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:48
79	235	((((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))) and (chip die ic)) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring)) not ("5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:49